

SE30200

**N-Channel Enhancement-Mode MOSFET**

Revision: A

**General Description**

Thigh Density Cell Design For Ultra Low On-Resistance Fully Characterized Avalanche Voltage and Current Improved Shoot-Through FOM

- Simple Drive Requirement
- Small Package Outline
- Surface Mount Device

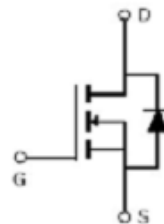
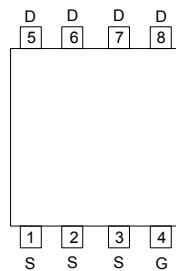
**Features**

For a single MOSFET

- $V_{DS} = 30V$
- $R_{DS(ON)} = 1.6m\Omega @ V_{GS}=10 @ I_{DS}=30A$
- $R_{DS(ON)} = 2.1m\Omega @ V_{GS}=4.5 @ I_{DS}=25A$

**Pin configurations**

See Diagram below



**Absolute Maximum Ratings**

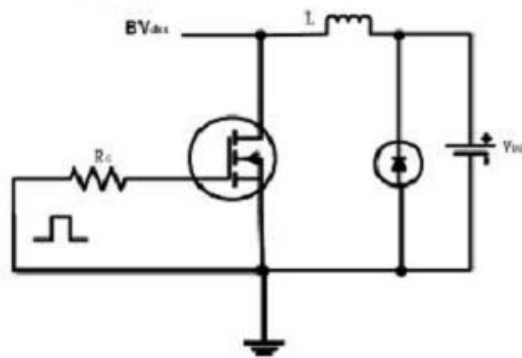
Parameter		Symbol	Rating	Units
Drain-Source Voltage		$V_{DS}$	30	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Drain Current	Continuous	$I_D$	200	A
	Pulsed		340	
Total Power Dissipation	@TA=25°C	$P_D$	90	W
Operating Junction Temperature Range		$T_J$	-55 to 150	°C

## SE30200

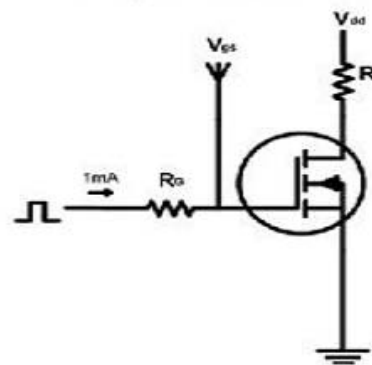
Electrical Characteristics (T <sub>J</sub> =25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS (Note 2)</b>						
B <sub>V</sub> DSS	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0 V	30			V
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>DS</sub> = 24V, V <sub>GS</sub> =0V			1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =20 V			100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	1	1.7	3.0	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	-	1.4	1.7	mΩ
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz		7032		pF
C <sub>oss</sub>	Output Capacitance			898		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			743		pF
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub>	Total Gate Charge <sup>2</sup>	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =30A		80		nC
Q <sub>gs</sub>	Gate Source Charge			19		nC
Q <sub>gd</sub>	Gate Drain Charge			38		nC
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>GEN</sub> =1Ω I <sub>D</sub> =1A		20		ns
t <sub>d(off)</sub>	Turn-Off Delay Time			80		ns
t <sub>d(r)</sub>	Turn-On Rise Time			36		ns
t <sub>d(f)</sub>	Turn-Off Fall Time			33		ns
<b>Thermal Resistance</b>						
Symbol	Parameter		Typ	Max		Units
R <sub>θJC</sub>	Junction to Case		-	2		°C/W
R <sub>θJA</sub>	Junction to Ambient (t ≤ 10s)		-	50		°C/W

Test Circuits and Waveform

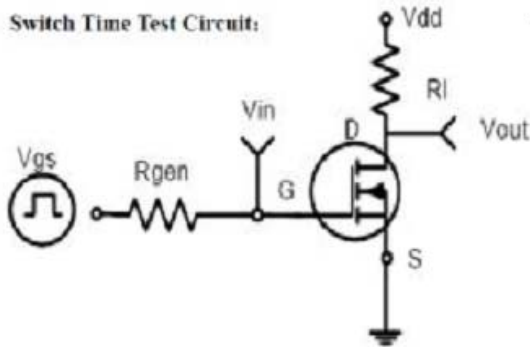
EAS test circuits:



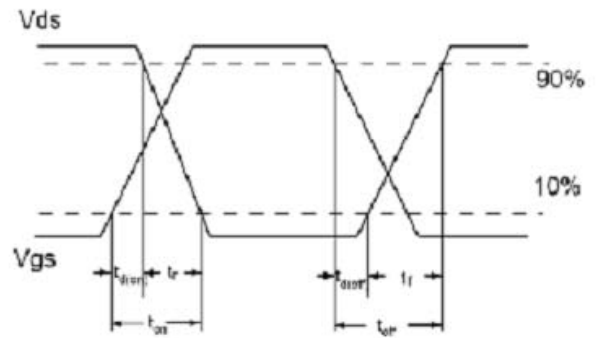
Gate charge test circuit:



Switch Time Test Circuit:



Waveforms:



Typical Characteristics

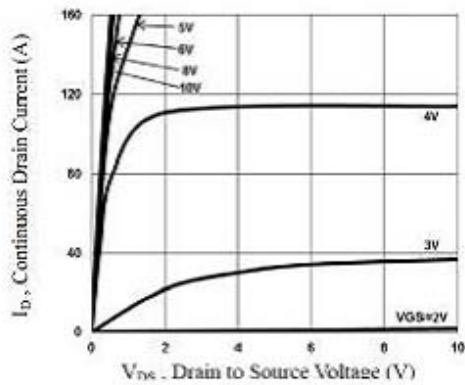


Figure 1: Typical Output Characteristics

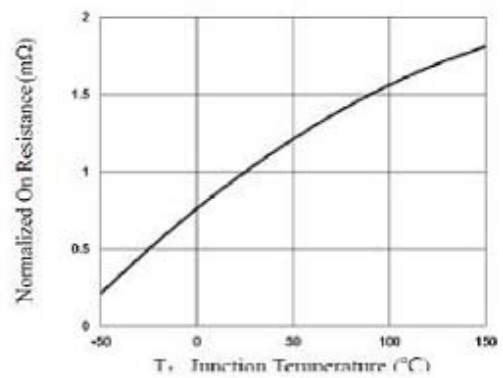


Figure 2: Normalized RDSON vs. TJ

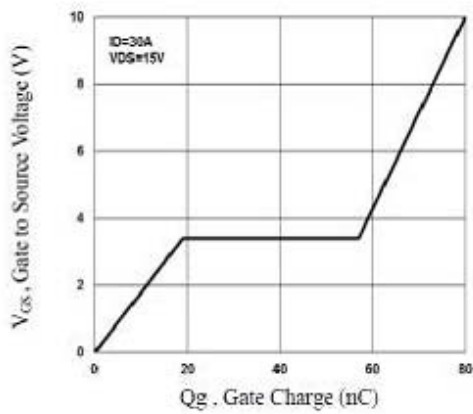


Figure 3: Gate-Charge Characteristics

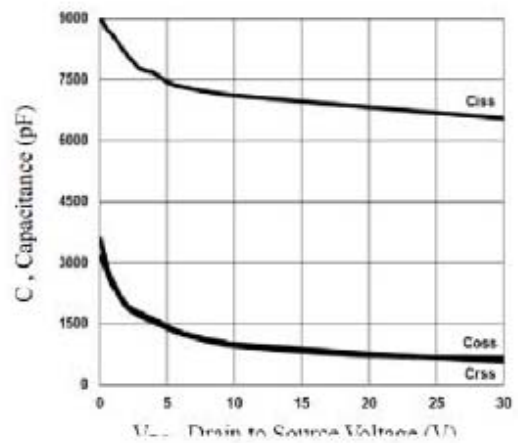


Figure 4: Capacitance Characteristics

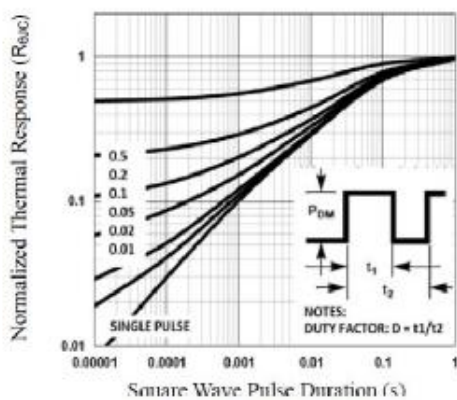


Figure 5: Normalized Thermal transient Impedance Curve

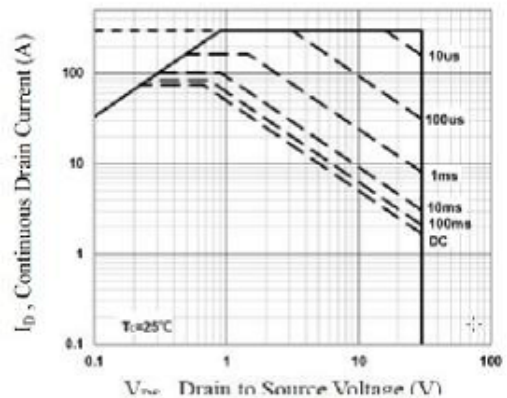
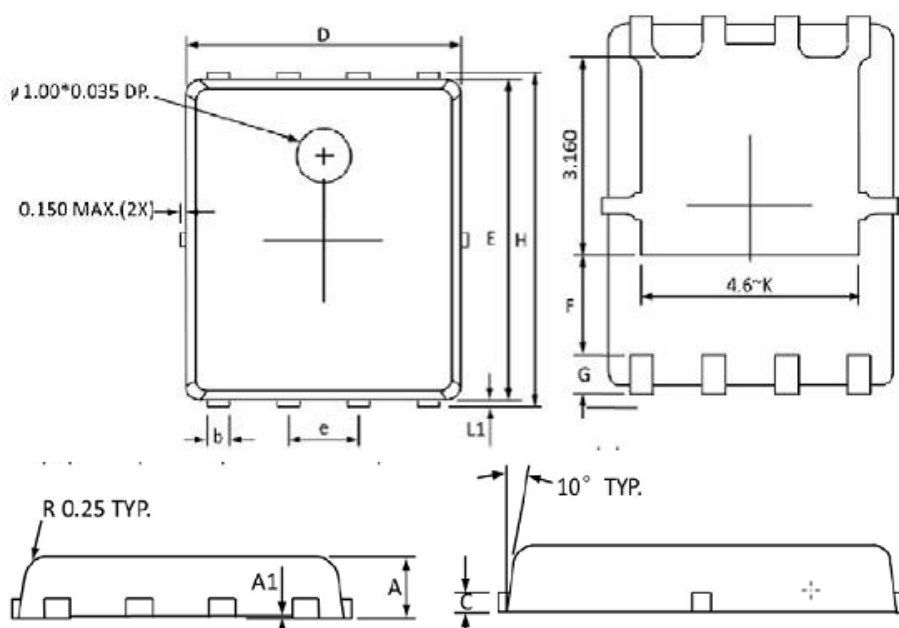


Figure 6: Maximum Safe Operation Area

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## Package Outline Dimension

### PPAK5X6



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.800	1.000	0.032	0.039
A1	0.000	0.005	0.000	0.000
b	0.350	0.490	0.014	0.019
C	0.254 Ref		0.254 Ref	
D	4.900	5.100	0.193	0.200
E	5.700	5.900	0.225	0.232
e	1.27 BSC		1.27 BSC	
F	1.600 Ref		1.600 Ref	
G	0.600 Ref		0.600 Ref	
H	5.950	6.200	0.235	0.244
L1	0.100	0.180	0.004	0.007
K	3.200 Ref		3.200 Ref	

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SHANGHAI SINO-IC MICROELECTRONICS CO., LTD

Add: Building 3, Room 3401-03, No.200 Zhangheng Road,  
ZhangJiang Hi-Tech Park, Pudong, Shanghai 201203, China

Phone: +86-21-33932402 33932403

33932405 33933508 33933608

Fax: +86-21-33932401

Email: [webmaster@sino-ic.com](mailto:webmaster@sino-ic.com)

Website: <http://www.sino-ic.com>